RETRACTION NOTE

Retraction Note: Solder Selection for Reflowing Large Ceramic Substrates During PCB Assembly

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This article has been retracted by the corresponding author as he did not have permission to publish the data. The editor has been unable to contact Noy Souriyasak regarding this retraction. The scientific content has been removed for legal reasons.

The retracted article can be found online at <https://doi.org/10.1007/s11668-017-0296-1>.

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